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OCP-IP Highlights Successful Implementation of Advanced OCP Features in Leading-Edge Designs

BEAVERTON, OR — April 12, 2011 - OCP-IP announces the successful adoption and implementation of sophisticated OCP interface features, including 2-dimensional (2-D) burst and power management, by innovative designs like the OMAP™ 4 platform from Texas Instruments Incorporated (TI).

Leveraging OCP in integrated circuit (IC) development allows designers to build their cores independent of specific bus protocols, and of any particular design implementation.

This ensures easier reuse of OCP-compliant cores across multiple system-on-chip (SoC) designs. OCP eliminates the need to repeatedly modify the core itself, and preserves fully reusable verification and test benches by defining all the core's natural interface capabilities to be presented in an unchanging, universally understood manner.

For the most sophisticated embedded multimedia and graphics processors demanding maximum memory system performance at minimum power consumption, the OCP protocol offers features such as 2-D bursts and safe core connect/disconnect for power

management. The advanced 2-D burst feature ensures the highest memory system performance for advanced graphics implementations, while the power management feature defines a new connection protocol that allows the power management hardware to disconnect the OCP interface without losing any transaction, so the manager may then independently shut off power. Detailed technical articles discussing the use of 2-D bursting and power management can be found by clicking on the links provided.

The first major SoC products using these sophisticated protocol features of the OCP protocol are now appearing on the market.

“TI’s OMAP 4 platform calls on the OCP’s 2-D burst feature to help improve DRAM efficiency for video and still image processing. Other OCP features such as core disconnect, out-of-order transaction completion, and single-request-multiple-data also benefit the OMAP 4 technology,” said James Aldis, MPU and DRAM Architecture Leader, Wireless Business Unit, TI. “These OCP components play a role in achieving the high performance and low power capabilities that make the OMAP 4 applications processor the industry’s most advanced mobile multimedia platform.”

The OMAP 4 platform is the fourth generation of TI’s OMAP family to utilize the OCP interface. The OMAP4430 processor contains more than 100 OCP-compliant building blocks.

TI is a Governing Steering Committee member of OCP-IP.

“OCP-IP not only provides the OCP specification, but also a complete infrastructure that allows our members to quickly and easily implement OCP into world-class leading edge designs like the OMAP platform,” said Ian Mackintosh, president OCP-IP. “Standards are

only proven through real-world implementations, and our member companies have adopted OCP and applied it in production SoC designs shipping approximately one billion units annually.”

To view some of the many application areas where OCP is used, please see the presentation available at: http://www.ocpip.org/ocp_inside.php.

About OCP-IP

Formed in 2001, OCP-IP is a non-profit corporation promoting, supporting and delivering the only openly licensed, core-centric protocol comprehensively fulfilling integration requirements of heterogeneous multicore systems. The Open Core Protocol (OCP) facilitates IP core reusability and reduces design time, risk, and manufacturing costs for all SoC and electronic designs by providing a comprehensive supporting infrastructure. For additional background and membership information, visit www.OCPIP.org.

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开源式内核协议国际同盟推出尖端设计中领先的开源式内核协议特性实现

比弗顿, 俄勒冈州—2011年4月12日—开源式内核协议国际同盟宣布成功采用并实现成熟的开源式内核协议接口特性, 德州仪器的OMAP™ 4平台创新设计的二维再现和电源管理。

利用开源式内核协议在集成电路(IC)领域的成果可以使设计人员建立自己的内核, 无需依赖于特定总线协议以及任何设计的实现, 这确保了在多个系统级芯片(SoC)设计中的OCP与内核之间更易兼容。OCP不需要反复修改内核本身, 并可充分保留验证的可重用性以及通过定义所有的内核自然接口功能来测试试验台得出一个稳定通用的数据。

最复杂的嵌入式多媒体图像处理器要求在最低的功耗时有最大的存储系统性能, 例如OCP协议提供二维再现和安全内核连接/断开电源管理功能。

先进的二维再现功能可以为尖端图像确保最高存储系统性能, 同时电源管理功能定义了一个新的连接协议, 可以使电源管理硬件与OCP接口断开连接时, 不损失任何的处理, 所以管理器可以单独切断电源。

第一个重要的使用OCP成熟的协议功能的SoC产品马上就要面世了。“德州仪器的OMAP 4平台使用了OCP的二维再现功能来提高视频以及静止图像处理中的DRAM效率。其他OCP核心功能, 例如内核断开, 故障处理, 单请求多数据技术也有利于OMAP 4”, 德州仪器无线事业部MPU和DRAM架构负责人James Aldis说“这些OCP功能能够实现高性能和低功耗, 可

以使 OMAP 4 应用处理器成为业内最先进的移动多媒体平台。”

OMAP 4平台是德州仪器OMAP系列使用OCP接口的第四代产品。OMAP4430处理器包含了超过100个OCP标准模块。

德州仪器是OCP-IP管理监督委员会会员。

“OCP-IP不仅提供OCP规范，也提供一个完整的基础架构来让我们的会员快速简单的完成像OMAP平台一样的世界一流的设计。”OCP-IP主席Ian Mackintosh 说 “标准只有通过实践证明，我们的会员公司已经通过采用OCP并将其应用到生产SoC设计中每年达到10亿次。

想要查看OCP所使用的应用，可点击：http://www.ocpip.org/ocp_inside.php.

关于OCP-IP

OCP国际联盟（OCP-IP）成立于2001年，是一家非盈利性企业，致力于促进、支持并提供唯一公开授权的、以核为中心的协议，用于满足包含不同种类的多个核的系统的集成需要。OCP提供一个获得广泛支持的基础架构，可以促进IP核的复用，为SoC设计和电子设计减少设计时间，降低风险和生产成本。了解更多的背景和会员信息，请访问

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